



HTEC8-160-01-S-DV-A

HTEC8-130-01-S-DV-A-WT

HTEC8-120-01-L-DV-A

HTEC8 SERIES

(0.80 mm) .0315"

RUGGED HIGH-SPEED EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HTEC8

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Operating Temp Range:

-55 °C to +125 °C

Current Rating:

3.0 A per pin

(2 pins powered)

Voltage Rating:

215 VAC

RoHS Compliant:

Yes

Mates with:
(1.60 mm) .062" thick card

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Accepts non-chamfered edge cards due to rugged tucked beam technology

Weld tab option

(0.80 mm) .0315" pitch



PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (20-60)

(0.13 mm) .005" max (80-100)*

*(.004" stencil solution may be available; contact

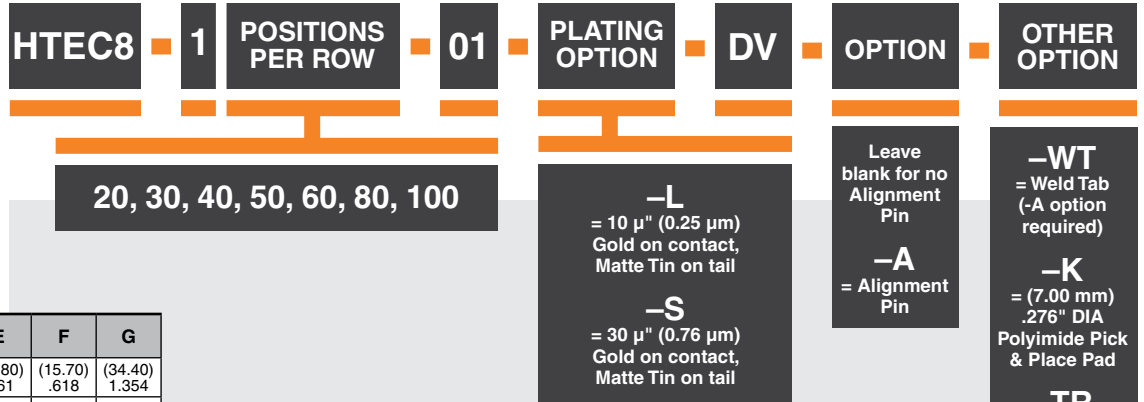
IPG@samtec.com)

RECOGNITIONS

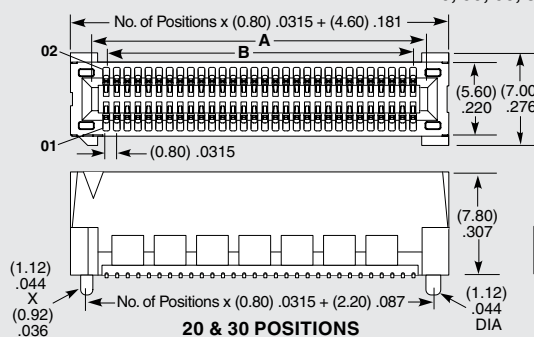
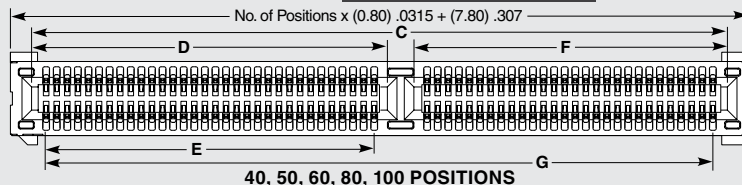
For complete scope of recognitions see www.samtec.com/quality



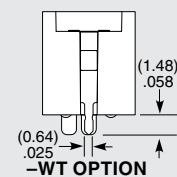
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POSITIONS PER ROW	C	D	E	F	G
40	(36.60) 1.440	(18.90) .744	(16.80) .661	(15.70) .618	(34.40) 1.354
50	(44.60) 1.756	(22.90) .902	(20.80) .819	(19.70) .776	(42.40) 1.669
60	(52.60) 2.071	(26.90) 1.059	(24.80) .976	(23.70) .933	(50.40) 1.984
80	(68.60) 2.701	(26.90) 1.059	(24.80) .976	(39.70) 1.563	(66.40) 2.614
100	(84.60) 3.331	(26.90) 1.059	(24.80) .976	(55.70) 2.193	(82.40) 3.244



POSITIONS PER ROW	A	B
20	(17.40) .685	(15.20) .598
30	(25.40) 1.000	(23.20) .913



Notes:
Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.